

PATENT NUMBER

O.I.P.E.

PATENT DATE

SCANNED

QA

APPLICATION NO.

CONT/PRIOR

CLASS

SUBCLASS

ART UNIT

| | |
|----------|--|
| EXAMINER | |
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Chih Liao

Method of electrically connecting semiconductor chip to solder balls on ball grid array package

PTO-2040
12/89

ORIGINAL

CROSS REFERENCE(S)

CLASS

SUBCLASS

CLASS

SUBCLASS (ONE SUBCLASS PER BLOCK)

INTERNATIONAL CLASSIFICATION

☐ Continued on Issue Slip Inside File Jacket

**TERMINAL
DISCLAIMER**

DRAWINGS

CLAIMS ALLOWED

Sheets Drwg.

Figs. Drwg.

Print Fig

Total Claims

Print Claim for O.G.

☒ The term of this patent subsequent to _____ (date) has been disclaimed.

☐ The term of this patent shall not extend beyond the expiration date of U.S. Patent. No. _____

☐ The terminal ____ months of this patent have been disclaimed.

(Assistant Examiner)

(Date)

(Primary Examiner)

(Date)

(Legal Instruments Examiner)

(Date)

NOTICE OF ALLOWANCE MAILED

ISSUE FEE

Amount Due

Date Paid

ISSUE BATCH NUMBER

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Form PTO-436A
(Rev. 6/99)

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(Attached in pocket on right inside flap)

(FACE)